

IN THE CLAIMS

Claims 14-19 have been cancelled.

The following claims are pending in the present application:

1. (Currently amended) A socket for a microelectronic component, comprising:

a socket body having a formation for receiving the microelectronic component and including at least a power metal portion, a ground metal portion and a dielectric portion;

a plurality of contacts on the socket body for making contact with corresponding lands of the microelectronic component;

a plurality of terminals on the socket body for connecting to corresponding connections on a carrier substrate;

a plurality of interconnection elements in the socket body, each interconnecting a respective contact with a respective terminal; and

a respective protrusion on each respective interconnection element, the each interconnection element and the respective protrusion being inserted into an opening in the socket body until the protrusion is in contact with either the ~~first~~ power metal portion, the ground metal portion, or the dielectric portion, a power set of the interconnection elements electrically connected to the metal power portion, a ground set of the interconnection elements all being electrically connected to the ground metal portion, and a signal set of the interconnection elements each being electrically

disconnected from both the power metal portion and the ground metal portion.

2. (Cancelled)

3. (Previously presented) The socket of claim 1, further comprising a stop component on the interconnection element to limit how far the interconnection element is inserted into the opening and to ensure that the protrusion is in line with the metal portion.

4. (Cancelled)

5. (Previously presented) The socket of claim 1, wherein the power metal portion is at a different elevation than the ground metal portion, at least some of the interconnection elements each being inserted into a respective opening in the socket body, the protrusions of the power set being in contact with the power metal portion and the protrusions of the ground set being in contact with the ground metal portion.

6. (Previously presented) The socket of claim 5, further comprising a stop component on each interconnection element to limit how far the respective interconnection element is inserted into the respective opening, the protrusion of each

interconnection element of the power set being at a first distance from the stop component and the protrusion of each interconnection element of the ground set being at a second distance, different to the first distance, from the stop component.

7. (Original) The socket of claim 6, wherein protrusions on the interconnection elements of the signal set contact the dielectric portion.

8. (Original) The socket of claim 1, further comprising a plurality of spring components on the interconnection element, each contact being on a respective spring component.

9. (Previously presented) The socket of claim 7, further comprising a plurality of solder balls each on a respective one of the interconnection elements, each terminal being on a respective solder ball.

10. (Currently amended) A socket for a microelectronic component, comprising:
a socket body having a horizontal base with upper and lower substantially horizontal sides and including at least a power metal portion, a ground metal portion and a dielectric portion, and side walls extending upward from the base, the side walls having inner surfaces jointly defining a recessed formation for receiving the

microelectronic component;

a plurality of electrically conductive contacts on the socket body at the upper horizontal side, spaced from one another for making contact with corresponding spaced lands of the microelectronic component;

a plurality of terminals on the socket body at the lower horizontal side, spaced from one another for connecting to corresponding connections on a carrier substrate;

a plurality of interconnection elements in the socket body, each extending between and interconnecting a respective one of the contacts with a respective one of the terminals; and

a respective protrusion on each interconnection element, the ~~respective~~ each interconnection element and the respective protrusion being inserted into an opening in the socket body until the protrusion is in contact with either the first power metal portion, the ground metal portion, or the dielectric portion, a power set of the interconnection elements electrically connected to the metal power portion, a ground set of the interconnection elements all being electrically connected to the ground metal portion, and a signal set of the interconnection elements each being electrically disconnected from both the power metal portion and the ground metal portion.

11. (Cancelled)

12. (Previously presented) The socket of claim 11, wherein the power metal portion is at a different elevation than the ground metal portion, at least some of the interconnection elements each inserted into a respective opening in the base, further comprising a protrusion on each of the respective interconnection elements, the protrusions of the power set being in contact with the power metal portion and the protrusions of the ground set being in contact with the ground metal portion.

13. (Previously presented) The socket of claim 12, further comprising a stop component on each interconnection element to limit how far the respective interconnection element is inserted into the respective opening, the protrusion of each interconnection element of the power set being at a first distance from the stop component and the protrusion of each interconnection element of the ground set being at a second distance, different to the first distance, from the stop component.

14.-19. (Cancelled)